JOCSR26BM-D5P/S Series

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The products are 5-pin solid-state relay opto-couplers. The device combines an AlGaAs infrared emitting diode as the emitter which is optically coupled to a monolithic silicon random-phase photo triac to drive a power triac in a plastic DIP5 package with different lead forming options. The products are widely used in solenoid/valve controls, lighting controls, motor controls, temperature controls, static AC power switches, solid state relays, interfacing microprocessors to 265VAC peripherals.

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High isolation 5000 Vrms
DC input with triac output
Operating temperature range -40 ‘ i M ɻ .D æg,

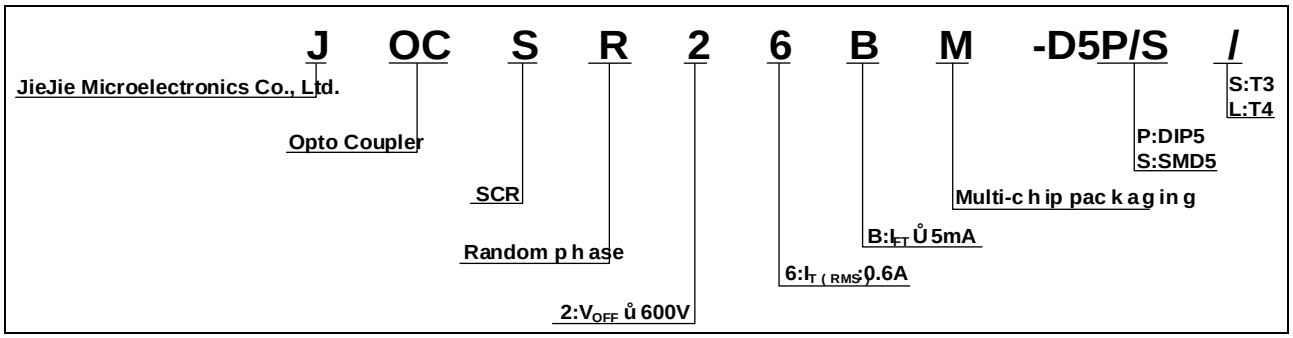
Isolation Voltage	V_{iso}	5000	Vrms
Operating Temperature	T_{opr}	-40 ~ 110	℃
Junction Temperature	T_j	125	℃
Storage Temperature	T_{stg}	-40 ~ 125	℃
Soldering Temperature	T_{sol}	260	℃
Peak pulse voltage (T=25℃ ; non-repetitive,off-state)	V_{pp}	3	kV

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Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	$_F$V	I_F = 10mA	-	1.2	1.5	V
	Reverse Current	$_R$	V_R = 6V	-	-	1	ε A
	Peak Off-state Current, Either Direction	I_{DRM}1	Direction				=
Output							

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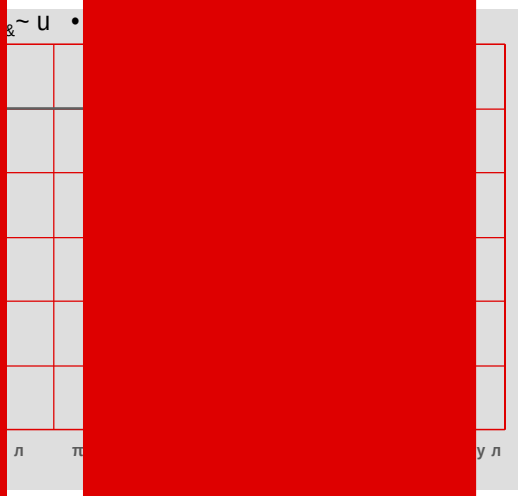
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.1: Ma urrent vs. FIG.2
bient Temp



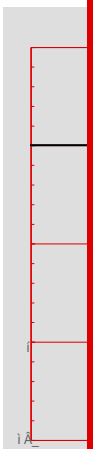


FIG.7: On-state c h aracteristics

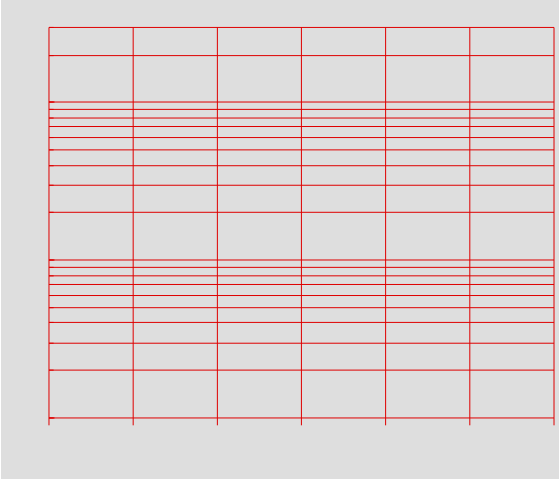
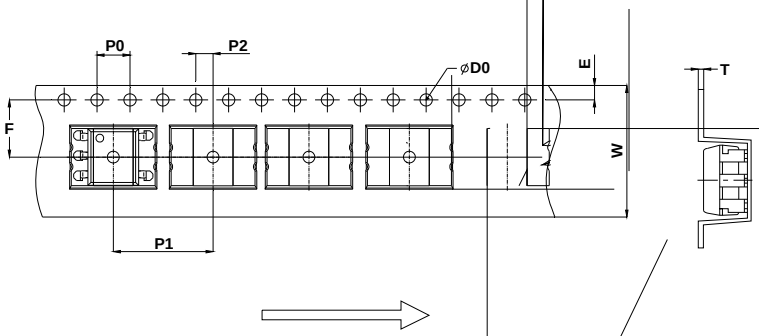


FIG.8: Normali z ed H oldin g Current vs. Ambient Temperature

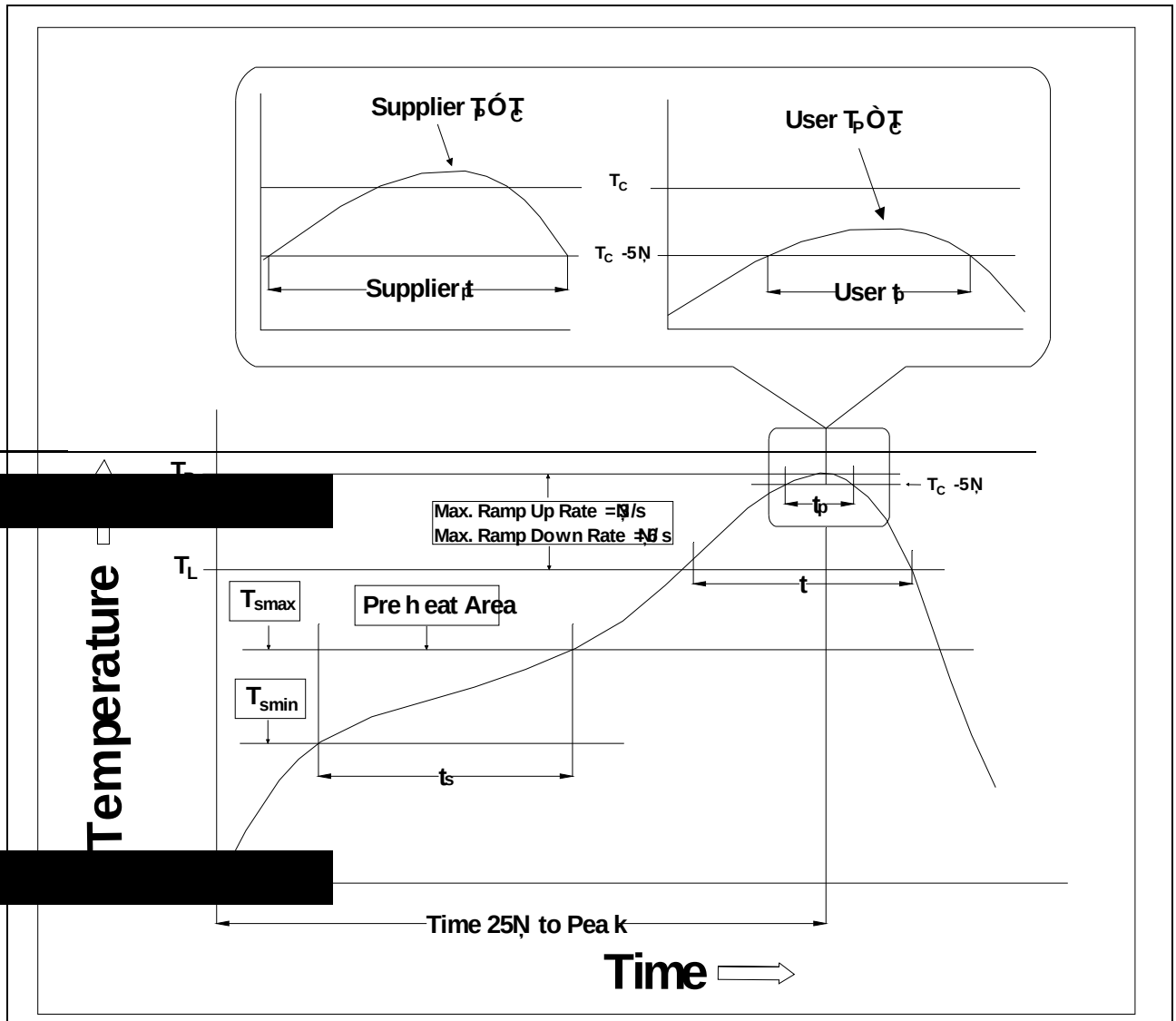
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Option S



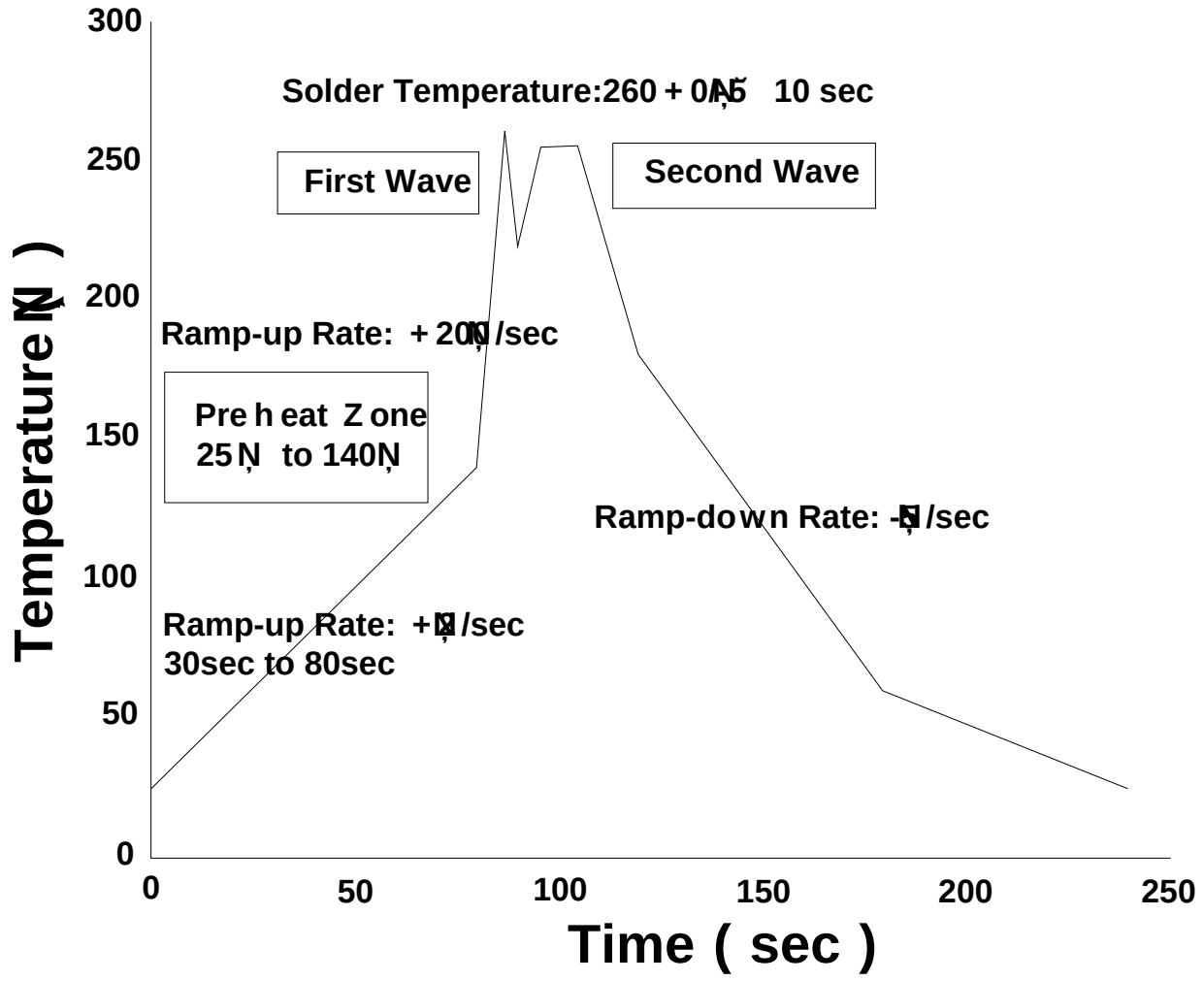
Ref.	Dimensions					
	Millimeters			Inch es		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.70	16.00	16.30	0.618	0.630	0.642

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Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	100Ñ	150Ñ
Temperature Max. (Tsmax)	150Ñ	200Ñ
Ramp-up Rate (tL to tP)	3Ñ/second max.	3Ñ/second max.
Li q uidus Temperature (TL)	183N	217N

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Soldering Temperature	360 ¤ 5
Soldering Time	3s max.

Note:

1. Reflow soldering is recommended at the temperatures and time shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum